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Date: 11/2/2014
P/N: PCB000892
Layers: 18
Total Thickness: 125.2mil +/-10%
Finish: Immersion silver

Stack-up and impedance requirements

Material: Panasonic Megtron 6 HVLP
PCB size and PCB units per array Board: 413 mm x 186mm \ 1 PCB Per Panel
PCB Utilization (%)
Gold finger: No
Back drill depth/width types on CS: 5
Back drill depth/width types on PS: 5



All dimensions are in mils unless otherwise stated

Layer	Copper parameters				Resin parameters				Impedance parameters						
	signal/ Power/ GND	Copper weight [oz]	Copper thickness after plating [Mil]	Copper roughness	Dielectric thickness	Material	Glass type	Resin content [%]	Differential pairs parameters			SE signal parameters			
									Imp. [Ω]	Default Width	Space	Neck-down Width	Space	Imp.[Ω]	Default Width
Layer 1 - CS	Signal	0.3333	1.8	HTE											
Prepreg					5.2	R5670K 1035(73)/1035(73)	1035	73	90±10%	7.1	5.15			55	8.1
Layer 2	GND	0.5	0.6	HVLP					95±10%	8.6	9.9				
Core					8	R5775K 8mils 2x3313 .5 oz / .5 oz	2x3313		95±10%	6	5				
Layer 3	Signal	0.5	0.6	HVLP					95±10%	5.9	5.35			55	5.9
Prepreg					6.3	R5670K 1078(68)/1078(68)	1078/1078	68	95±10%	7.63	13.37				
Layer 4	GND	0.5	0.6	HVLP					90±10%	7.15	6.35				
Core					8	R5775K 8mils 2x3313 .5 oz / .5 oz	2x3313								
Layer 5	Signal	0.5	0.6	HVLP					95±10%	5.9	5.35			55	5.9
Prepreg					6.3	R5670K 1078(68)/1078(68)	1078/1078	68	95±10%	7.63	13.37				
Layer 6	GND	0.5	0.6	HVLP					90±10%	7.15	6.35				
Core					8	R5775K 8mils 2x3313 .5 oz / .5 oz	2x3313								
Layer 7	Power	0.5	0.6	HVLP											
Prepreg					6.2	R5670K 1078(68)/1078(68)	1078/1078	68							
Layer 8	Power	1	1.2	RTF											
Core					4	R5775K 4mils 1x3313 1 oz / 2 oz	1x3313								
Layer 9	Power	2	2.4	RTF											
Prepreg					3.2	R5670K 1035(73)/1035(73)	1035	73							
Layer 10	Power	2	2.4	RTF											
Core					4	R5775K 4mils 1x3313 1 oz / 2 oz	1x3313								
Layer 11	GND	1	1.2	RTF											
Prepreg					6.2	R5670K 1078(68)/1078(68)	1078/1078	68							
Layer 12	Signal	0.5	0.6	HVLP					95±10%	5.85	5.4			55	5.8
Core					8	R5775K 8mils 2x3313 .5 oz / .5 oz	2x3313		95±10%	7.5	13.5				
Layer 13	GND	0.5	0.6	HVLP					90±10%	7.05	6.45				
Prepreg					6.3	R5670K 1078(68)/1078(68)	1078/1078	68							
Layer 14	Signal	0.5	0.6	HVLP					95±10%	5.9	5.35			55	5.9
Core					8	R5775K 8mils 2x3313 .5 oz / .5 oz	2x3313		95±10%	7.63	13.37				
Layer 15	GND	0.5	0.6	HVLP					90±10%	7.15	6.35				
Prepreg					6.3	R5670K 1078(68)/1078(68)	1078/1078	68							
Layer 16	Signal	0.5	0.6	HVLP					95±10%	5.9	5.35			55	5.9
Core					8	R5775K 8mils 2x3313 .5 oz / .5 oz	2x3313		95±10%	7.63	13.37				
Layer 17	GND	0.5	0.6	HVLP					90±10%	7.15	6.35				
Prepreg					5.2	R5670K 1035(73)/1035(73)	1035	73							
Layer 18 - PS	Signal	0.3333	1.8	HTE					90±10%	7.1	5.15			55	8.1
									95±10%	8.6	9.9				
									95±10%	6	5				

If you have any queries please do not hesitate to contact:
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Revision control:		
Revision	Date	Description
00	11/2/2014	First release

Notes:	
1	The dielectric thickness, line widths and differential space values are nominal values. Minor changes can be done to meet the impedance requirements.(HW desiner approval is a must)
2	Trace widths are nominal finished dimensions.